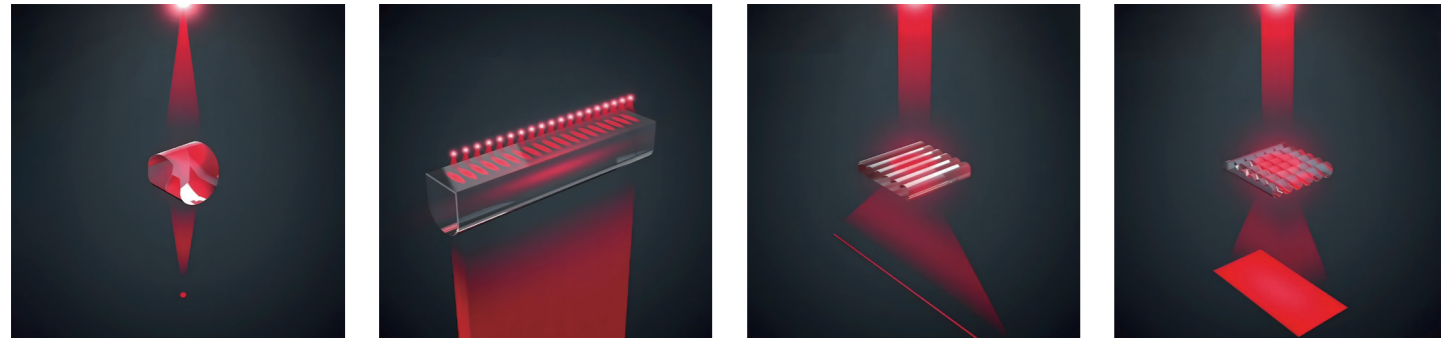
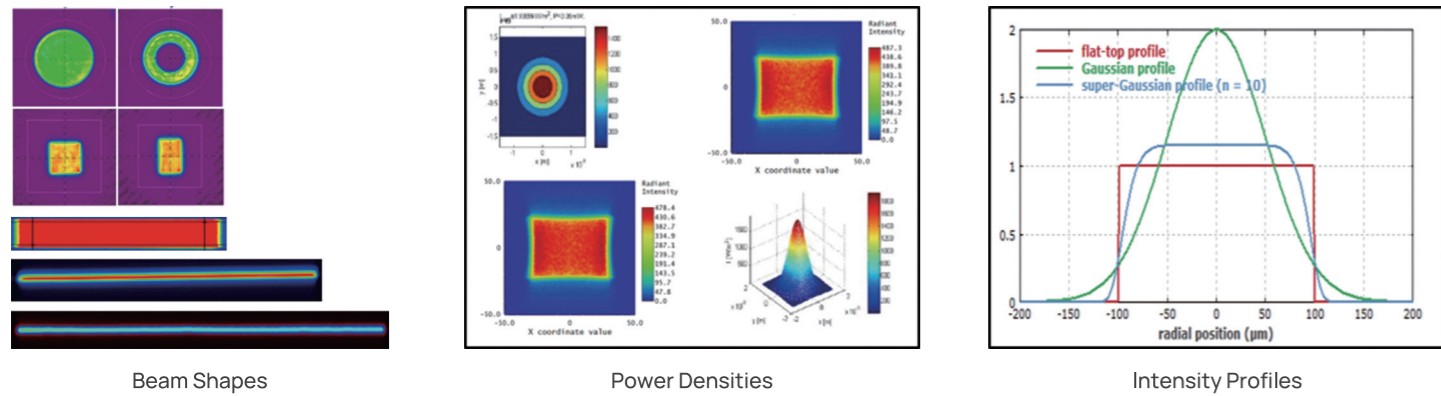


Direct Application of Diode Lasers with Advanced Beam Shaping Technologies

Taking advantage of beam shaping technologies, we can manipulate the output beam shapes, power densities, and intensity profiles that are most essential for laser-matter interactions. With low cost and high efficiency, the direct application of diode laser has become a clever option in specific scenarios.

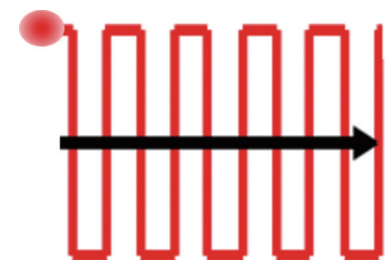


Optical solutions for zero dimension (dot), one dimension (line) and two dimension (area)

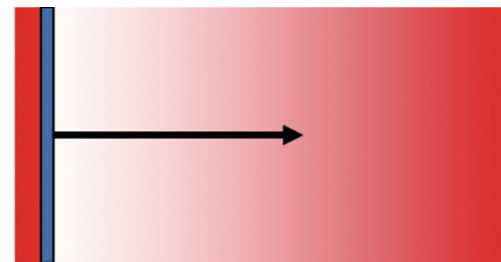


Revolution of Laser Applications: From Dot to Line and Area

Pulsed or continuous laser sources, powered by beam-shaping micro-optics, can significantly enhance production efficiency compared to conventional point-shaped beams. By selecting the optimal beam shape, power density, and light intensity distribution, the best application performance and maximum value can be achieved.



Conventional point laser scanning:
Beam must walk through both directions
to cover the whole area



Advanced line laser scanning:
Beam only needs to go through one direction
to cover the whole area



COMPANY INTRODUCTION

Founded in 2007 and headquartered in Xi'an, China, Focuslight Technologies Inc. is a fast-growing public company (Shanghai: 688167) that specializes in developing and manufacturing high-power diode laser components and materials, laser optics, as well as photonics module and system solutions focusing on optical communication, automotive, pan-semiconductor, and medical and health applications. Focuslight has expanded its global footprint through strategic acquisitions including LIMO GmbH in 2017 and SUSS MicroOptics SA in 2024 (now as Focuslight Switzerland SA). With the acquisition of assets from ams OSRAM in 2024, Focuslight extends its business to be a global photonics foundry by providing global photonics industry process development and manufacturing service under the brand of Heptagon. Learn more at www.focuslight.com and www.hptg.com.



www.focuslight.com

Focuslight Technologies Inc.

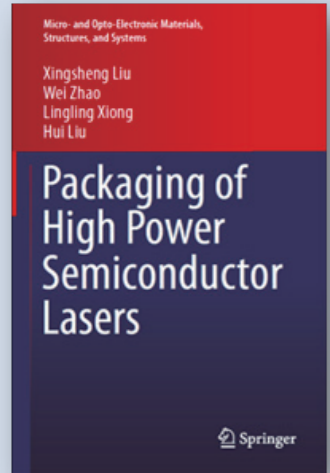
Email: sales@focuslight.com

High-Power Diode Laser

COMPONENTS AND MATERIALS

Focuslight - Diode laser light source leader and beam shaping expert with strong IP position

Since its establishment, Focuslight has been dedicated to the research and development of fundamental photonics components and related application solutions. Our core technologies enable us to provide strong supports to our partners' business and together drive the growth and prosperity of the photonics industry worldwide.



Eutectic Bonding

High Reliability

Carrier with Pre-deposited AuSn solder layer

Solder

Heatsink

Thermal Management

Finite Element Thermal Analysis and Design

Thermal Stress Control

Interface Materials and Surface Engineering

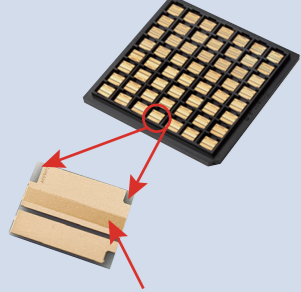
Solder nonwetting

Solder wetting

Test, Analysis and Diagnosis

Advanced Materials

Fabricated through pre-deposition of micron-level AuSn thin film in specific areas of substrate materials, these substrates are the key to the long-term reliability of high-power diode laser chips and components. Focuslight is one of the pioneers in AuSn thin film deposition and AuSn bonding with more than ten years of expertise.



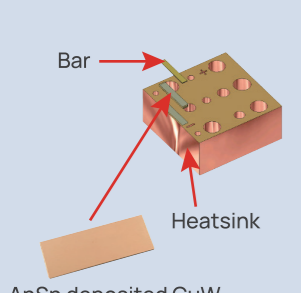
AuSn deposited area

AuSn Pre-deposited AlN Substrates

Specifications	Value
Mostly Used Dimensions	L: 4.0 - 10.0 mm, W: 2.0 - 5.0 mm, T: 0.2 - 2.0 mm Flexible customization available
AuSn Thickness	4.5 ± 1 μm
Melting Point	280 - 320 °C
Thermal Resistance	≤ 2 K/W

Key Benefits

- Low thermal resistance
- High matching CTE
- High precision surface
- High precision wafer processing
- High thermal conductivity
- Low warpage



Bar

Heatsink

AnSn deposited CuW

AuSn Pre-deposited CuW Substrates

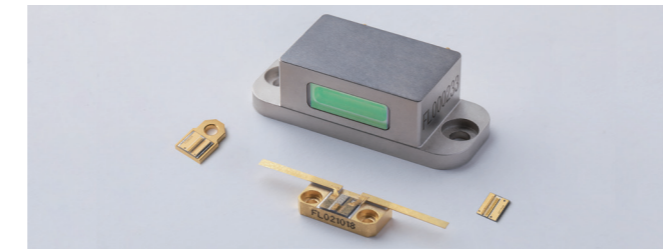
Specifications	Value
Mostly Used Dimensions	L: 4.0 - 10.0 mm, W: 2.0 - 5.0 mm, T: 0.2 - 2.0 mm Flexible customization available
AuSn Thickness	6.0 ± 1 μm
Melting Point	280 - 320 °C
AuSn Deposition Side	Single / double sided

Typical Application Scenarios

- Laser diode chip bonding
- LED chip bonding
- Optical communication chip bonding
- IGBT component bonding
- Other metallization service

Single Emitters and Bars

Focuslight offers high-power single-emitter diode lasers with structures of COC (chips on carrier), NV02 with dust-proof design, the Focuslight patented F-mount, as well as our high-power single-bar diode lasers based on micro-channel cooling or conduction-cooling designs.



Single Emitter Diode Lasers

Specifications	Value
Typical Power Output	10W 808nm CW 12W 915/940/976nm CW 5W 1470nm CW
Available Wavelengths	660/808/915/940/976/1470 nm
Fast Axis Collimation	1:1 or 1:2 optional, or customizable

Typical Application Scenarios

- Illumination
- Range finding
- Medical treatment
- Side pumping / end pumping (e.g. Nd:YAG / Nd:YVO4 laser, Yb:YAG / Er:YAG laser)



Single Bar Diode Lasers

Specifications	Value
Typical Power Output	60W 808nm CW 100W 940/976/980nm CW 80W 1060nm CW 30W 1470nm CW
Smile	< 2 μm (typical); < 1 μm (new LCS series)
Cooling	Water-cooled or conduction-cooled

Diode Laser Stacks

We offer high-power micro-channel water-cooled and conduction-cooled stacks with various structures differing in sizes, bar arrangement and electrical designs, covering wavelengths from 760 to 1060 nm and a wide power output range.



Micro-Channel Water Cooled Diode Laser Stacks

Specifications	Value
Typical Power Output	100W/bar CW 808nm, 200W/bar CW 940nm
Smile	< 2 μm (typical)
Number of Bars	Up to 60 bars per stack
Fast Axis Collimation	Optional

Typical Application Scenarios

- Hair removal
- Laser annealing
- Side pumping / end pumping (e.g. Tm laser, Nd:YAG / Nd:YVO4 laser, Yb:YAG laser)



G-Stacks and G-Stack-Based Arrays

Specifications	Value
Typical Power Output	200-500W/bar QCW, 808/940nm
Duty Cycle	< 1% or few percent
Operation Temperature	-45 ~ 60 °C
Fast Axis Collimation	Optional

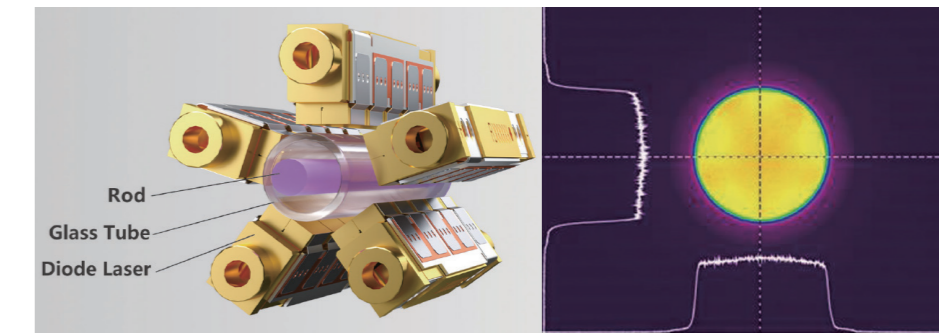
Diode Laser Side Pumped Modules

Featuring our advanced high-power diode laser as core component, along with our unique designs of optics, water flow, and ASE (amplified spontaneous emission) effect control, our side pumped modules ensure high-power DPSSLs with outstanding performance, reliability and efficiency.



Side pumped modules: SP17 and SP18

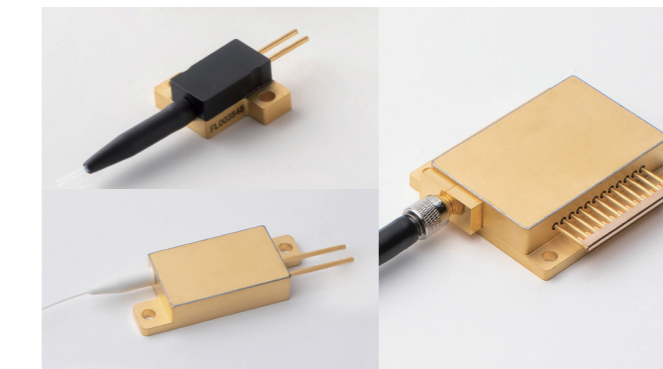
Specifications	SP17	SP18
Typical Power Output	30 kW QCW	5 kW QCW
Rod Diameter	10 mm	4 mm
Number of Bars	150	25
Small Signal Gain (SSG)	> 55	> 30



Five phase pumping used in SP17/SP18 (left); Typical fluorescence imaging (right)

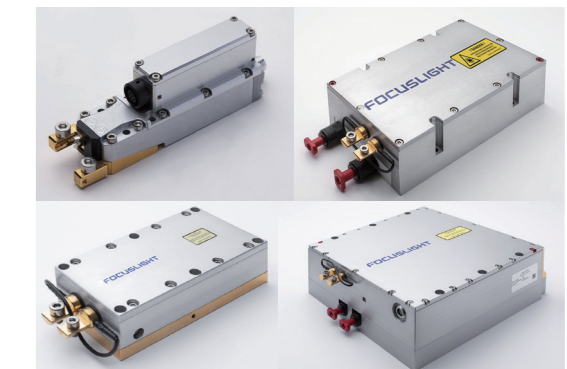
Fiber Coupled Modules

Our fiber coupled diode laser modules, based on either multiple single laser emitters or laser bars with conduction-cooled or water-cooled designs, provide highly efficient, flexible and reliable solutions to various application scenarios like advanced manufacturing, medical, and scientific research.



Emitter-based fiber coupled modules: FCSE08, FCMSE58, FCMSE55 series

Specifications	Value
Power Output	Up to 30W 808/976/1064 nm
Fiber Core Diameter	105/200 μm
Numerical Aperture	0.15/0.22
Optional Functions	Fiber detection, power detection, pilot beam



Bar-based fiber coupled modules: LM, FG, ND, MF series

Specifications	Value
Power Output	Up to 500W 808/940/976 nm
Fiber Core Diameter	100/200/400 μm
Numerical Aperture	0.22
Optional Functions	Fiber detection, negative temperature coefficient thermistor, power detection, pilot beam, feedback reflection, VBG